

**CHIP-PACKAGING WITH BONDING OPTIONS CONNECTED TO A
PACKAGE SUBSTRATE**

Appl. No. : 10/709,428 Confirmation No. 3427
Applicant : Cheng-Yen Huang
Filed : May 5, 2004
TC/A.U. : 2814
Examiner : TRINH, HOA B
Docket No. : FTCP0035USA0
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

AMENDMENT

5 Sir:

In response to the Office action of July 28, 2006, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 6 of this paper.